

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHARP LABORATORIES OF AMERICA, INC.	09/15/2017
RECEIVING PARTY DATA	
Name:	SHARP KABUSHIKI KAISHA
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15859672
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	SLA3629.1
NAME OF SUBMITTER:	HATTIE E. GOLDIE
SIGNATURE:	/Hattie E. Goldie/
DATE SIGNED:	03/07/2018
Total Attachments: 1	
source=SLA3629 Assignment to SKK#page1.tif	

CORPORATE-TO-CORPORATE ASSIGNMENT

WHEREAS, Sharp Laboratories of America, Inc. (hereinafter "SLA"), a corporation of the State of Washington, having a place of business at 5750 NW Pacific Rim Boulevard, Camas, Washington 98607, is, by an assignment document recorded in the assignment records of the United States Patent and Trademark Office, at Reel / Frame: 039759 / 0855, the present assignee and record owner of an invention entitled:

“Substrate Features for Enhanced Fluidic Assembly of Electronic Devices”

invented by David Robert Heine et al. (hereinafter "said Invention"), including a US patent application filed by SLA on September 15, 2016, Serial No. 15/266,796, pertaining thereto (hereinafter "the ‘796 application");

WHEREAS, Sharp Kabushiki Kaisha (hereinafter “Sharp”), a Japanese Corporation, having an address at 1 Takumi-cho, Sakai-ku, Sakai City, Osaka 590-8522, Japan, is the parent company and owner of SLA; and

WHEREAS, SLA and Sharp wish to transfer ownership of said Invention, including the ‘796 application, from SLA to Sharp;

NOW THEREFORE, for good and valuable consideration acknowledged by SLA to have been received in full from Sharp, SLA does hereby sell, assign, transfer, convey, and quitclaim unto Sharp all of SLA’s right, title and interest in and to said Invention, including the ‘796 application.

The terms and covenants of this Assignment shall inure to the benefit of Sharp, its successors, assigns and other legal representatives, and shall be binding upon SLA, its successors, assigns and other legal representatives.

The undersigned is authorized to act on behalf of the present assignee, SLA.

Sharp Laboratories of America, Inc.

Dated: September 15, 2017

/David C. Ripma/
David C. Ripma, Registration No. 27,672
Patent Counsel of MiiCs IP, Inc., a subsidiary of
SBPJ Co., Ltd. and Sharp Corporation